Jameco Part Number 801932

FEATURES AND SPECIFICATIONS

2.54mm (.100") Pitch SL™ Wire-to-Board Shrouded Header

70545

Single Row, .120" Pocket Vertical, Tri-Peg

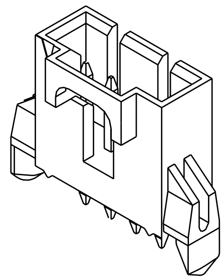
Features and Benefits
- Size 2 to 25 circuits
- PCB locks hold header in place until permanently soldered
- Locking crown secures positive latch to header
- Polarization slots guide front ribs of mating connector to prevent pin damage
- Standoffs minimize flux retention
- Surface Mount Compatible

Reference Information
Product Specification: PS-70541
Packaging: Tube
UL File No.: E29179
CSA File No.: LR19980
Mates With: 70066G, 70066N, 70400G and 70430G
Designed In: Inches

Electrical
Voltage: 250V
Current: 3.0A
Contact Resistance: 15mΩ max.
Dielectric Withstanding Voltage: 1500V
Insulation Resistance: 1000 MΩ min.

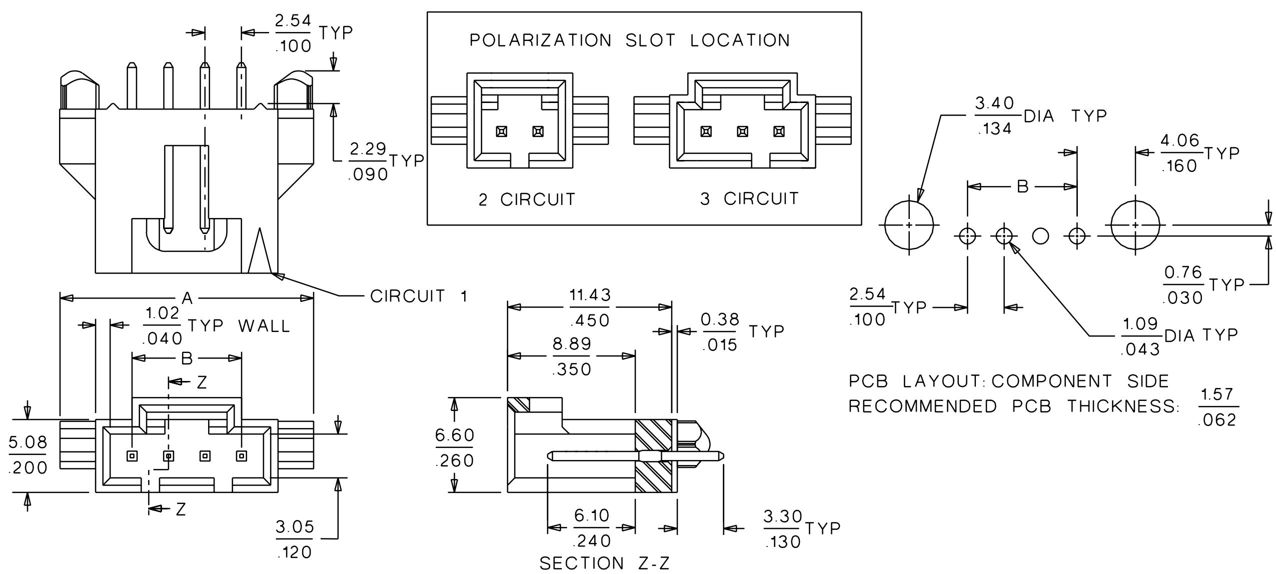
Mechanical
Insertion Force to PCB: 44.50N (10 lb)
Durability: 25 cycles Tin and 50 cycles Gold

Physical
Housing: Black glass-filled PCT, UL 94V-0
Contact: Phosphor Bronze, .025" square
Plating: See Table
Operating Temperature: -40 to +105˚C



CATALOG DRAWING (FOR REFERENCE ONLY)

Not For Use With C-Grid III™ Components



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.			Dimension	
	15µ" Min. Gold	30µ" Min. Gold	150µ" Tin/Lead	A	B
2	• 70545-0036	70545-0071	70545-0001	12.40 (.488)	2.54 (.100)
3	• 70545-0037	70545-0072	70545-0002	14.94 (.588)	5.08 (.200)
4	• 70545-0038	70545-0073	70545-0003	17.48 (.688)	7.62 (.300)
5	• 70545-0039	70545-0074	70545-0004	20.02 (.788)	10.16 (.400)
6	• 70545-0040	70545-0075	70545-0005	22.56 (.888)	12.70 (.500)
7	• 70545-0041	70545-0076	70545-0006	25.10 (.988)	15.24 (.600)
8	• 70545-0042	70545-0077	70545-0007	27.64 (1.088)	17.78 (.700)
9	• 70545-0043	70545-0078	70545-0008	30.18 (1.188)	20.32 (.800)
10	• 70545-0044	70545-0079	70545-0009	32.72 (1.288)	22.86 (.900)
11	• 70545-0045	70545-0080	70545-0010	35.26 (1.388)	25.40 (1.000)
12	• 70545-0046	70545-0081	70545-0011	37.80 (1.488)	27.94 (1.100)
13	• 70545-0047	70545-0082	70545-0012	40.34 (1.588)	30.48 (1.200)

Circuits	Order No.			Dimension	
	15µ" Min. Gold	30µ" Min. Gold	150µ" Tin/Lead	A	B
14	• 70545-0048	70545-0083	70545-0013	42.88 (1.688)	33.02 (1.300)
15	• 70545-0049	70545-0084	70545-0014	45.42 (1.788)	35.56 (1.400)
16	• 70545-0050	70545-0085	70545-0015	47.96 (1.888)	38.10 (1.500)
17	• 70545-0051	70545-0086	70545-0016	50.50 (1.988)	40.64 (1.600)
18	• 70545-0052	70545-0087	70545-0017	53.04 (2.088)	43.18 (1.700)
19	• 70545-0053	70545-0088	70545-0018	55.58 (2.188)	45.72 (1.800)
20	• 70545-0054	70545-0089	70545-0019	58.12 (2.288)	48.26 (1.900)
21	• 70545-0055	70545-0090	70545-0020	60.66 (2.388)	50.80 (2.000)
22	• 70545-0056	70545-0091	70545-0021	63.20 (2.488)	53.34 (2.100)
23	• 70545-0057	70545-0092	70545-0022	65.74 (2.588)	55.88 (2.200)
24	• 70545-0058	70545-0093	70545-0023	68.28 (2.688)	58.42 (2.300)
25	• 70545-0059	70545-0094	70545-0024	70.82 (2.788)	60.96 (2.400)

• US Standard Product, available through Molex franchised distributors

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1.**0** ***SCOPE***

This specification is intended to define the mechanical, electrical and environmental requirements for the SL .100” (2.54) pitch modular, single row wire-to-board and wire-to-wire system.

SL is designed for high density signal applications. The system includes: low profile latching vertical and right angle headers; low profile housings for male and female crimp terminals; pre-assembled, single piece pin and receptacle connectors for Insulation Displacement Technology (IDT); panel mounts for modular wire-to-wire remote interconnections; and SL offers design flexibility and automated harness-making capabilities when combined with our tooling.

2.0 ***PRODUCT DESCRIPTION:***

2.1 The following Series are covered by this product specification:

70021, male, crimp terminal
70058, female box, crimp terminal
71851, female box, high force crimp terminal
70066 & 70107, single row, crimp housing
70450 & 74130, dual row, crimp housing
70400, female, single row, insulation displacement, connector assembly
70475 & 71178 ,male, single row, insulation displacement, connector assembly
70543, single row, .120” pocket, wire-to-board, shrouded header, vertical
70541, single row,.120” pocket, wire-to-board, shrouded header, vertical, split peg
70545, single row,.120” pocket, wire-to-board, shrouded header, vertical, tri-peg
70553, single row,.120” pocket, wire-to-board, shrouded header, right angle
70555, single row,.120” pocket, wire-to-board, shrouded header, right angle, tri-peg
70563, single row, .180” pocket, wire-to-board, shrouded header, vertical
70565, single row,.180” pocket, wire-to-board, shrouded header, vertical, tri-peg
70573, single row,.180” pocket, wire-to-board, shrouded header, right angle
70575, single row,.180” pocket, wire-to-board, shrouded header, right angle, tri-peg

2.2 DIMENSIONS, MATERIALS AND SPECIFICATIONS:

2.2.1 Mating Pin Height

2.2.1.1 Maximum mating pin height: .320” (8.13 mm)
2.2.1.2 Minimum mating pin height: .200” (5.08 mm)

2.2.2 Centerline spacing (pitch): .100” (2.54 mm)

2.2.3 Wire Sizes: #22 - #28 AWG stranded wire, with an insulation diameter of .053” (1.35 mm) max.

2.2.4 Molex cable: 7307, 7767, 8996, 8997, 24226, 24241, 24369 and 24389.

2.2.5 Termination Method:

2.2.5.1 Crimp (70021, 70058)
2.2.5.2 IDT (70400, 70475)

2.2.6 Housings: (70066, 70450, 70107, 74130): Black Glass Filled Polyester, UL 94V-0

2.2.7 Terminals: (70021, 70058): Phosphor Bronze

2.2.7 Plating: Gold and Tin

2.2.7.1 Gold: 30 μ-in. min. Gold in select area over Nickel overall with 75 μ-in. Tin in select area over Nickel overall
or
Gold: 15 μ-in. min. Gold in select area over Nickel overall with 75 μ-in. Tin in select area over Nickel overall
2.2.7.2 Tin: 150 μ-in. min. Tin over Nickel overall.

See the appropriate Sales Drawing(s) for additional information on dimensions, materials, platings, and markings.

2.3 SAFETY AGENCY APPROVALS:

UL File Number E29179
CSA File Number LR19980

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS:

All documents referenced shall be of the latest revision. The order of precedence shall be as follows.

- Product Drawings
- This product specification
- Reference documents

3.1 REFERENCE DOCUMENTS:

- EIA 364 Electronic Industries Association, Recommended Standard
- MIL-STD-202: Test methods for electronics and electrical component parts.
- UL-94: Tests for flammability of plastic material

4.0 RATINGS:

4.1 VOLTAGE:

250 V

4.2 CURRENT:

1.2 A - 28 AWG
1.8 A - 26 AWG
3.0 A - 24 AWG
3.0 A - 22 AWG

4.2 TEMPERATURE:

Operating: -40 °C to +105 °C
Processing: See chart on next page.

5.0 PERFORMANCE:

5.1 ELECTRICAL PERFORMANCE:

Item	Test Condition	Requirement
Contact Resistance (Low Level)	Mate Connectors with a maximum voltage of 20mV and a current of 100 mA.	**30** milliohm Maximum Initial
Insulation Resistance	Mate Connectors with a voltage of **500** VDC between adjacent terminals and between terminals and ground.	**1000** Megohms Minimum
Dielectric Withstanding Voltage	Mate Connectors with a voltage of 1500 VAC for 1 min. between adjacent terminals and between terminals and ground.	No breakdown
Capacitance	Measure between adjacent terminals at **1** MHz. (Loaded: 50 ohms impedance)	Loaded: **2** picofarad max. Unloaded: 0.5 picofarad max.

5.2 MECHANICAL PERFORMANCE:

Item	Test Condition	Requirement
Terminal Insertion and Withdrawal Forces	Insert and withdraw a terminal (male to female) at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.	70058 - Insertion force shall be 4.45 N (1.0 lb) max. and withdrawal 0.56 N (0.125 lb) min. 71851 - Insertion force shall be 13.34 N (3.0 lb) max. and withdrawal 1.67 N (0.375 lb) min
Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.	Contact : 17.79 N (4.0 lbs.) min.
Durability	Mate connectors up to 25 cycles for tin plating and 50 cycles for gold plating at a maximum rate of 10 cycles per minute prior to defined Environmental Tests.	Contact Resistance : 10 milliohms Maximum Change from Initial

Item	Test Condition	Requirement
Vibration Mil-Std-1344 Method 2005.1 Condition I	Amplitude: 1.50mm (.060 inch) peak to peak Sweep: 10-55-10 Hz in one minute Duration: 2 hours in each X-Y-Z axis. (Test module shall be per Section 7.0)	Contact Resistance: 10 milliohms Maximum Change from Initial Discontinuity: not greater than one microsecond
Mechanical Shock Mil-Std-1344 Method 2004.1 Condition A	50 g's with three 1/2 sine wave form shocks in each X-Y-Z axis. (Test module shall be per Section 8.2)	Contact Resistance: 10 milliohms Maximum Change from Initial Discontinuity: not greater than one microsecond
Wire Pullout Force (Axial)	Apply an axial pullout force on the wire at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.	Pullout force - 75% tensile strength of wire, minimum.
Wire Pullout Force (Right Angle)	Apply a right angle pullout force on the wire at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.	Pullout force - 75% tensile strength of wire, minimum. 20 Newton's and below - no plastic deformation / no electrical discontinuity Above 20 and below 60 Newton's - slight non-functional plastic deformation / no electrical discontinuity.
Terminal Insertion Force (into Housing)	Apply an axial insertion force on the terminal at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.	13.34 N (3.0 lbs) maximum insertion force.
Wire Flex	Flex cable 180° for 500 cycles.	Contact resistance: 10 milliohms Maximum Change from Initial. Appearance: No Damage
Normal Force	Apply a perpendicular force at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute on the contacts in a manner simulating actual use.	0.49 N (50 grams) minimum end of life, for gold plating 0.98 N (100 grams) minimum end of life, for tin plating.
Connector Retention	Apply a perpendicular force of 45 N to the wire harness using a free hanging weight.	No deformation or Terminal separation

5.3 ENVIRONMENTAL PERFORMANCE

Item	Test Condition	Requirement
Thermal Shock Mil-Std-202F Method 107 E	Mate connectors exposed to 10 cycles of: Temperature °C Duration (Min) -40 +0/-3 30 +25 +/-10 5 Max +105 +3/-0 30 +25 +/-10 5 Max -40 +0/-3 30	Appearance: No Damage Contact Resistance: 10 milliohms maximum change from initial
Thermal Aging Mil-Std-202F Method 108	Mate connectors; expose to 240 hours at 105 ± 3° C	Appearance: No Damage Contact Resistance: 10 milliohms maximum change from initial
Humidity (Steady State) Mil-Std-202F Method 103	Mate connectors; expose to a temperature of : 85 ± 2°C with a Relative Humidity of 92 ± 3% for 96 hours. Note: Remove surface moisture and air dry for 1 hour prior to measurements.	Appearance: No Damage Contact Resistance: 10 milliohms maximum change from initial. Dielectric Withstanding Voltage: No Breakdown Insulation Resistance: 1000 Megohms Minimum

Item	Test Condition	Requirement
Humidity (Cyclic) Mil-Std-202 Method 105	Mate connectors; expose for 10 cycles at 90-98% relative humidity with a transition time of 2.5 hours between extremes: Temperature °C — Duration (Min) +25 ± 10 — 5 maximum +65 +3/-0 — 15 maximum Note: Remove surface moisture and air dry for one hour prior to measurements.	Appearance: No Damage Contact Resistance: 10 milliohms maximum change from initial. Dielectric Withstanding Voltage: No Breakdown Insulation Resistance: 1000 Megohms Minimum
Temperature Rise and Current Cycling	Temperature Rise: Mate the connectors; and measure the temperature rise at the rated current after 96 hours. Current Cycling: Mate connectors; measure the temperature rise at the rated current after 500 hours (45 minutes ON and 15 minutes OFF per hour).	Temperature Rise: 30°C above ambient maximum Temperature Rise: 30°C above ambient maximum
Solderability Molex SMES-152	Steam age 1 hr. Solder time 5 ± 0.5 seconds. Solder temperature: 245 ± 5°C Non activated flux.	95% of the immersed area must show no voids, pin holes
Flowing Mixed Gas (FMG)	Battelle Class II, 10 ppm Cl_2, 10 ppm H_2S, 100 ppm NO_2, 70 ± 1% R.H., 25 deg. C. 50-60 CFM. 10 days mated and 7 days unmated exposure.	Contact Resistance: 10 milliohms Maximum change from Initial
Resistance to Solder Heats	Solder Time 3 ± 0.5 seconds Solder Temperature: 260 ± 5°C Immerse leads to a depth of 1.57mm (.062 in.) from connector body.	Appearance: No damage or discoloration of connector materials.

6.0 PACKAGING:

Parts are packaged in trays, tubes or bulk packed, refer to appropriate Sales Drawing for specific information.

7.0 QUALITY ASSURANCE PROVISIONS:

7.1 MATERIAL INSPECTION:

Shall consist of certification supported by verifying data.

7.2 ACCEPTANCE INSPECTION:

Acceptance of ongoing production product shall be determined by inspection according to Molex approved quality plans and required PPM levels for critical characteristics.

7.3 CONFORMANCE TESTING:

Shall be performed on production quality manufactured products. Sample size shall be per 8.1.

7.4 Gages:

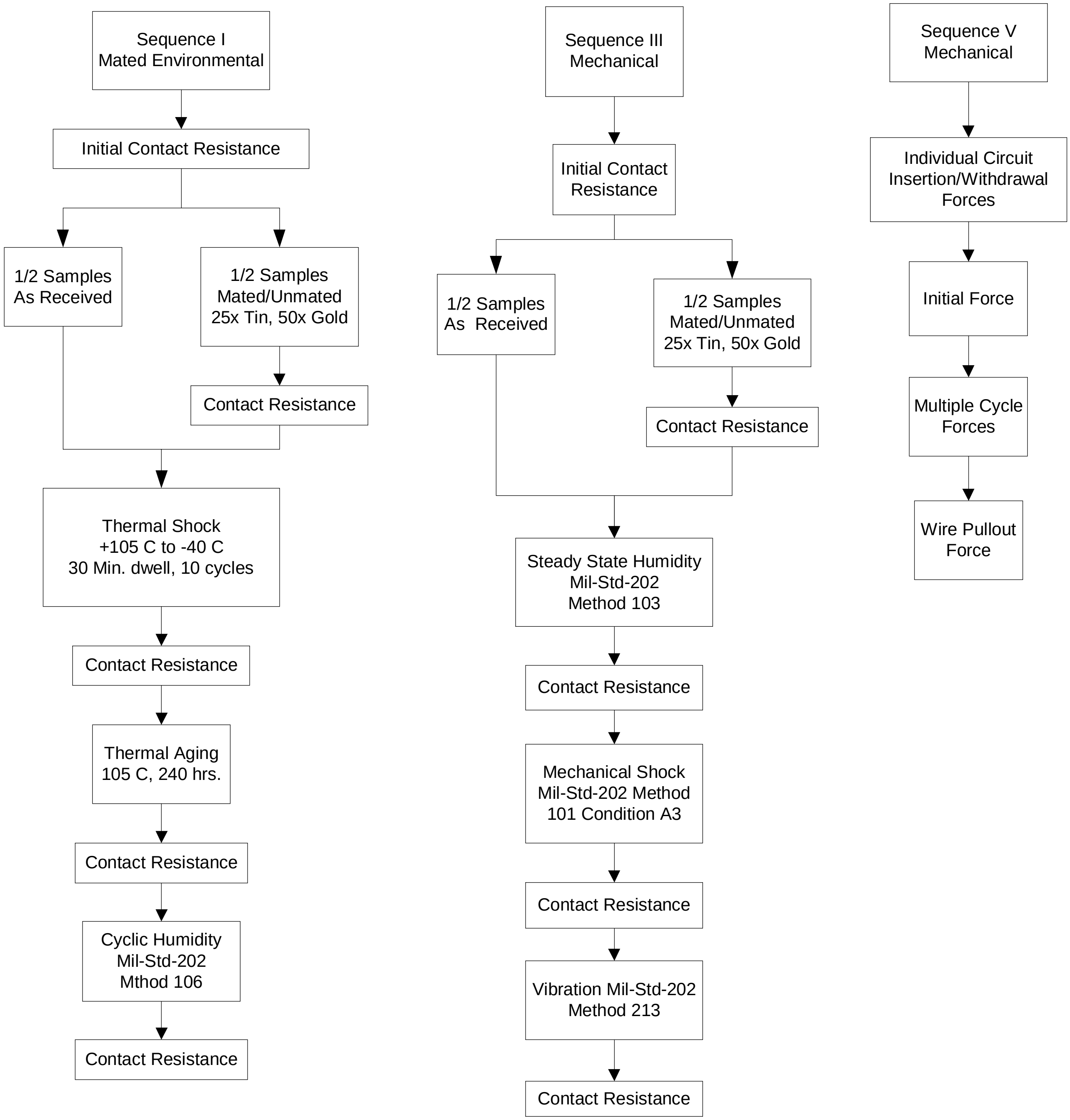
Terminal insertion/withdrawal testing should be performed with the gage pin detailed below.

8.0 QUALIFICATION REQUIREMENTS:

8.1 QUALIFICATION TESTING:

1. Samples for testing shall be representative of normal production lots.

2. Sample groups shall consist of a minimum (5) mated pairs of headers and receptacles. 30 minimum data points per group shall be measured. Measurements shall be taken from the middle and ends of the connectors as a minimum.



Sequence I
Mated Environmental
Initial Contact Resistance
1/2 Samples
As Received
1/2 Samples
Mated/Unmated
25x Tin, 50x Gold
Contact Resistance
Thermal Shock
+105 C to -40 C
30 Min. dwell, 10 cycles
Contact Resistance
Thermal Aging
105 C, 240 hrs.
Contact Resistance
Cyclic Humidity
Mil-Std-202
Mthod 106
Contact Resistance
Sequence III
Mechanical
Initial Contact
Resistance
1/2 Samples
As Received
1/2 Samples
Mated/Unmated
25x Tin, 50x Gold
Contact Resistance
Steady State Humidity
Mil-Std-202
Method 103
Contact Resistance
Mechanical Shock
Mil-Std-202 Method
101 Condition A3
Contact Resistance
Vibration Mil-Std-202
Method 213
Contact Resistance
Sequence V
Mechanical
Individual Circuit
Insertion/Withdrawal
Forces
Initial Force
Multiple Cycle
Forces
Wire Pullout
Force

9.0 TEST SUMMARY:

9.1 SEQUENCE I - MATED ENVIRONMENTAL:

TEST CONDITION	TREATMENT	REQUIREMENT	UNITS	MEAN	MINIMUM	MAXIMUM
Contact Resistance	Initial	30 max.	milliohms	14.47	13.77	15.08
	After Durability	10 max. Change from initial	Δ-milliohms	.09	-0.82	1.40
	After Shock (Thermal)	10 max. Change from initial	Δ-milliohms	.02	-1.15	1.32
	After Thermal Aging	10 max. Change from initial	Δ-milliohms	.00	-1.06	1.18
	After Humidity (Cyclic)	10 max. Change from initial	Δ-milliohms	.25	-1.00	1.78

9.2 SEQUENCE III - MECHANICAL:

TEST CONDITION	TREATMENT	REQUIREMENT	UNITS	MEAN	MINIMUM	MAXIMUM
Contact Resistance	Initial	30 max.	milliohms	8.6	8.0	9.4
	After Humidity (Steady State)	10 max. Change from initial	Δ-milliohms	8.6	8.0	9.6
	After Shock (Mechanical)	10 max. Change from initial	Δ-milliohms	8.7	8.1	9.9
	After Vibration	10 max. Change from initial	Δ-milliohms	8.7	8.1	9.4

9.3 ENVIRONMENTAL PERFORMANCE:

TEST CONDITION	TREATMENT	REQUIREMENT	UNITS	MAXIMUM
Temperature Rise and Current Cycling (+30°C)	22 AWG	**** Minimum	Amps	3
	24 AWG	**** Minimum	Amps	3
	26 AWG	**** Minimum	Amps	1.8
	28 AWG	**** Minimum	Amps	1.2
	30 AWG	**** Minimum	Amps	0.70
	32 AWG	**** Minimum	Amps	0.45
	34 AWG	**** Minimum	Amps	0.32
	36 AWG	**** Minimum	Amps	0.21

9.4 SEQUENCE V - MECHANICAL:

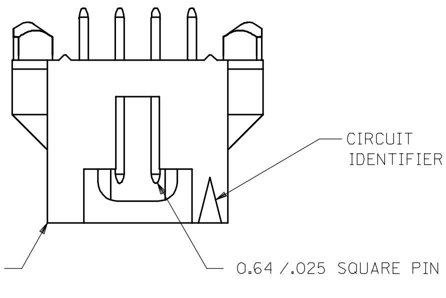
70058 - MATING FORCE SEQUENCE 5.3						
TEST CONDITION	**TREATMENT**	**PLATING**	**UNITS**	**MEAN**	**MINIMUM**	**MAXIMUM**
Insertion Force	Initial	Tin	LB/(N)	0.73/(3.24)	0.62/(2.74)	0.82/(3.63)
		Gold	LB/(N)	0.39/(1.75)	0.28/(1.25)	0.59/(2.62)
	After 25 Cycles	Tin	LB/(N)	0.75/(3.32)	0.64/(2.83)	0.89/(3.94)
	After 50 Cycles	Gold	LB/(N)	0.44/(1.96)	0.27/(1.19)	0.55/(2.44)
Withdrawal Force	Initial	Tin	LB/(N)	0.97/4.31)	0.79/(3.52)	1.05/(4.65)
		Gold	LB/(N)	0.29/(1.28)	0.20/(0.89)	0.44/(1.97)
	After 25 Cycles	Tin	LB/(N)	0.77/(3.43)	0.68/(3.04)	0.90/(4.02)
	After 50 Cycles	Gold	LB/(N)	0.38/(1.69)	0.29/(1.29)	0.56/(2.50)

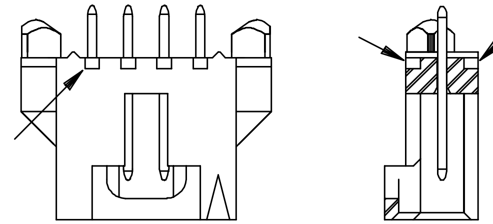
71851 - MATING FORCE SEQUENCE 5.3						
TEST CONDITION	**TREATMENT**	**PLATING**	**UNITS**	**MEAN**	**MINIMUM**	**MAXIMUM**
Insertion Force	Initial	Tin	LB/N	2.39/10.62	2.24/9.96	2.53/11.25
		Gold	LB/N	0.99/4.39	0.91/4.05	1.05/4.67
	After 25 Cycles	Tin	LB/N	2.18/9.71	1.60/7.12	2.82/12.54
	After 50 Cycles	Gold	LB/N	1.01/4.48	0.86/3.83	1.17/5.20
Withdrawal Force	Initial	Tin	LB/N	2.68/11.92	2.28/10.14	3.18/14.15
		Gold	LB/N	0.69/3.07	0.62/2.76	0.77/3.43
	After 25 Cycles	Tin	LB/N	2.70/12.02	1.79/7.96	4.23/18.82
	After 50 Cycles	Gold	LB/N	1.07/4.76	0.84/3.74	1.25/5.56

TEST CONDITION	TREATMENT	PLATING	UNITS	MEAN	MINIMUM	MAXIMUM
Wire Pullout Force (Axial)	22 AWG with strain relief	**** Minimum	N/LB	65.3/14.67	56.2/12.63	72.4/16.28
	22 AWG w/o strain relief	**** Minimum	N/LB	48.0/10.78	39.2/8.81	54.5/12.24
	24 AWG	**** Minimum	N/LB	37.0/8.32	28.5/6.40	44.9/10.10
	26 AWG	**** Minimum	N/LB			
	28 AWG	**** Minimum	N/LB			
	30 AWG	**** Minimum	N/LB			
	32 AWG	**** Minimum	N/LB			
	34 AWG	**** Minimum	N/LB			
	36 AWG	**** Minimum	N/LB			

9.5 MISCELLANEOUS:

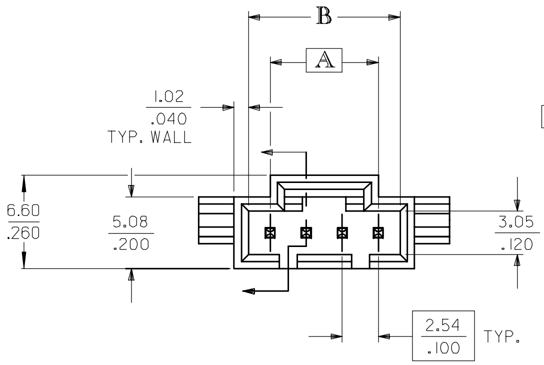
TEST CONDITION	TREATMENT	REQUIREMENT	UNITS	MEAN	MINIMUM	MAXIMUM
Terminal Retention Force (in Housing)	Initial	**** Minimum	N/LB	37.94/8.53	23.04/5.18	55.74/12.53
Insulation Resistance	Initial	1000 Min.	Megaohms	Passed		
	After Shock (Thermal)	1000 Min.	Megaohms	Passed		
	After Thermal Aging	1000 Min.	Megaohms	Passed		
	After Humidity (Steady State)	1000 Min.	Megaohms	Passed		
	After Humidity (Cyclic)	1000 Min.	Megaohms	Passed		

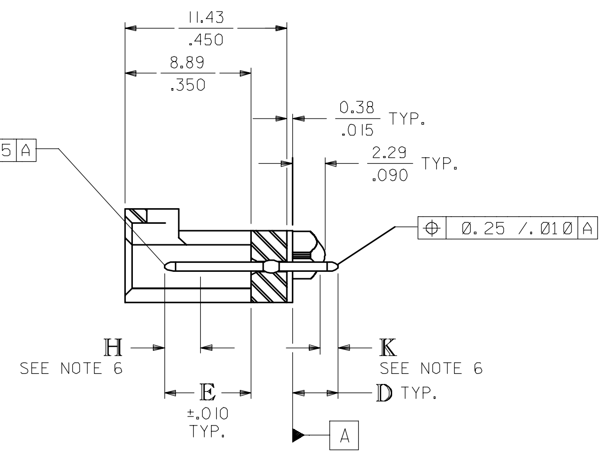


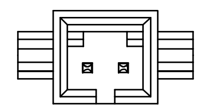


ALTERNATIVE CORING MANUFACTURER'S OPTION

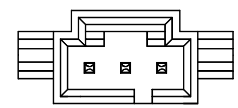
CKT. SIZE	DIM. "A" MM	DIM. "A" IN.	DIM. "B" MM	DIM. "B" IN.
2	2.54	.100	5.33±0.08	.210±.003
3	5.08	.200	8.13±0.10	.320±.004
4	7.62	.300	10.67±0.10	.420±.004
5	10.16	.400	13.21±0.10	.520±.004
6	12.70	.500	15.75±0.10	.620±.004
7	15.24	.600	18.29±0.10	.720±.004
8	17.78	.700	20.83±0.10	.820±.004
9	20.32	.800	23.37±0.10	.920±.004
10	22.86	.900	25.91±0.13	1.020±.005
11	25.40	1.000	28.45±0.13	1.120±.005
12	27.94	1.100	30.99±0.13	1.220±.005
13	30.48	1.200	33.53±0.13	1.320±.005
14	33.02	1.300	36.07±0.13	1.420±.005
15	35.56	1.400	38.61±0.15	1.520±.006
16	38.10	1.500	41.15±0.15	1.620±.006
17	40.64	1.600	43.69±0.15	1.720±.006
18	43.18	1.700	46.23±0.15	1.820±.006
19	45.72	1.800	48.77±0.18	1.920±.007
20	48.26	1.900	51.31±0.18	2.020±.007
21	50.80	2.000	53.85±0.18	2.120±.007
22	53.34	2.100	56.39±0.18	2.220±.007
23	55.88	2.200	58.93±0.18	2.320±.007
24	58.42	2.300	61.47±0.18	2.420±.007
25	60.96	2.400	64.01±0.20	2.520±.008



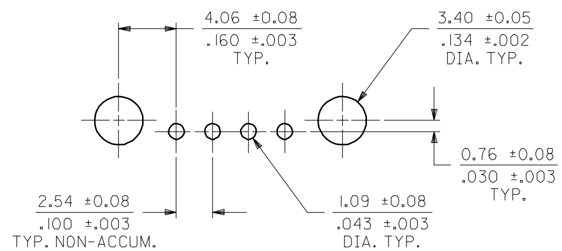




2 CIRCUIT



3 CIRCUIT



RECOMMENDED PC BOARD LAYOUT

(FOR USE WITH 1.57 /.062 THICK BOARD)

NOTES:

1. HEADER MATERIAL: GLASS FILLED POLYESTER, UL94V-0, COLOR: BLACK
   PIN MATERIAL: PHOSPHOR BRONZE
2. FINISH:
   TIN - 0.00381/.000150 MIN TIN PLATE
   OVER 0.00127/.000050 MIN NICKEL PLATE
   15 GOLD - 0.00038/.000015 MIN GOLD PLATE IN SELECT AREA,
   0.00191/.000075 MIN TIN PLATE IN SELECT AREA,
   OVER 0.00127/.000050 MIN NICKEL PLATE OVERALL.
   30 GOLD - 0.00076/.000030 MIN GOLD PLATE IN SELECT AREA,
   0.00191/.000075 MIN TIN PLATE IN SELECT AREA,
   OVER 0.00127/.000050 MIN NICKEL PLATE OVERALL.
   * THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC." CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
3. PRODUCT SPECIFICATION: PS-70541
4. PACKAGING SPECIFICATION: PK-70873-0014
5. HEADER TO BE USED WITH OPTION "G" 70400 AND 70430 SERIES SL CONNECTORS.
6. MEASURE POINT FOR PLATING THICKNESS.
7. DIMENSIONS WTHOUT TOLERANCE ARE SHOWN FOR REFERENCE ONLY.

SHT	REV
4	G1
3	H
2	F1
1	I

REV	DESCRIPTION
I	CLARIFY DIM. EC NO: UCP2007-0673 DRWN:MSIBARRA 2006/09/15 CH'KD:DMORGAN 2006/09/15 APPR:SMILLER 2006/09/19

QUALITY SYMBOLS: ▼=0, ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.005
2 PLACES	± 0.13	±.01
1 PLACE	± 0.25	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN — SCALE: 4:1 — DESIGN UNITS: INCH — THIRD ANGLE PROJECTION

		DATE
DRAWN BY	AAB	05/12/93
CHECKED BY	MJM	05/12/93
APPROVED BY	WAZ	05/12/93

TITLE: SALES ASSY, SL VERTICAL HEADER W/LATCH&TRI-PEGS (2.54)/.100 CENTERS

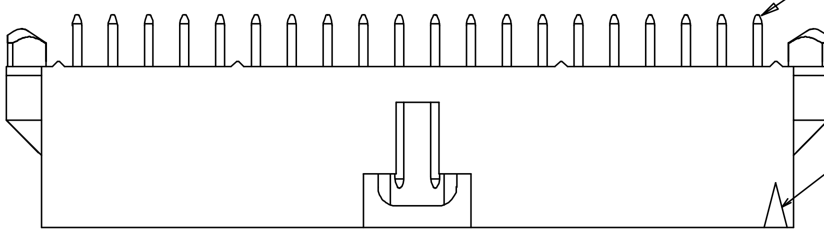
molex — MOLEX INCORPORATED

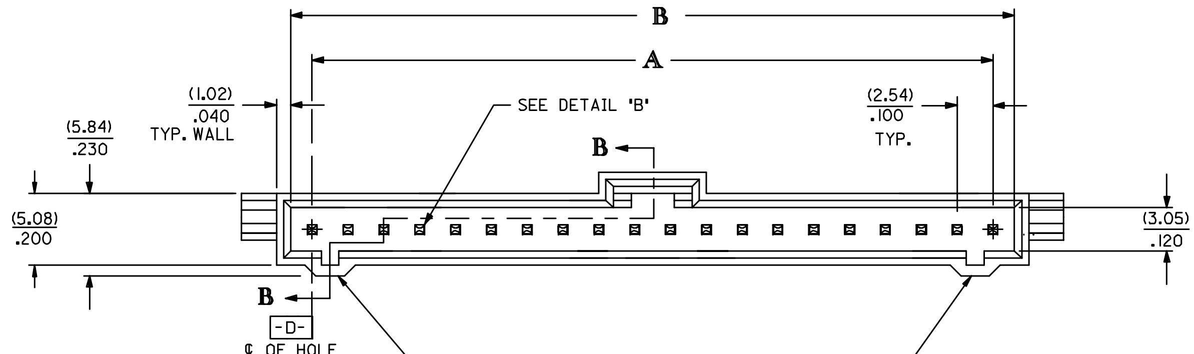
MATERIAL NO.: SEE CHART — DOCUMENT NO.: SDA-70545-**** — SHEET NO.: 1 OF 4 — SIZE: C

OPTIONAL HOUSING

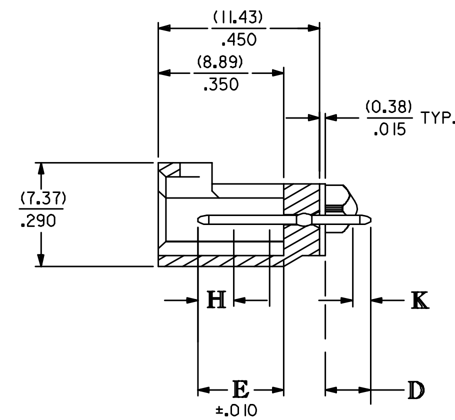
WEBBED KEYING FEATURES

20 CKT HEADER
SHOWN FOR REFERENCE





WEBBED KEYING FEATURES



SECTION B-B

UPDATE TITLE BLOCK EC NO: UCP2006-0202 DRWN:JLOWE 2005/08/05 CH'KD:ADERR 2005/08/05 APPR:FSMITH 2005/08/09	DESCRIPTION	
F1	REV	

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.005
2 PLACES	±0.13	±.01
1 PLACE	±0.25	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN	SCALE: ---	DESIGN UNITS: INCH	THIRD ANGLE PROJECTION
DRAWN BY: WGM	DATE: 07/10/96	TITLE: SALES ASSY, SL VERTICAL HEADER W/LATCH&TRI-PEGS (2.54)/.100 CENTERS	
CHECKED BY: WGM	DATE: 07/10/96		
APPROVED BY: WAZ	DATE: 07/10/96	MOLEX INCORPORATED	
MATERIAL NO.: SEE CHART		DOCUMENT NO.: SDA-70545-****	SHEET NO.: 2 OF 4
SIZE: C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

CIRCUIT SIZE	ASSEMBLY ITEM NUMBER 70545	MANUFACTURE RELEASE STATUS				D (± 0.38) ± .015	E (± 0.25) ± .010		CONNECTOR END PLATING TYPE	H MEAS.		P.C. BOARD END PLATING TYPE	K MEAS.		
2-10	-0001-0009	R.F.M.				(3.30) .130	(6.10) .240		TIN	(2.54) .100		TIN	(1.27) .050		
11-25	-0010-0024	R.F.M.													
2-10	-0036-0044	R.F.M.				(3.30) .130	(6.10) .240		15 GOLD	(2.54) .100		TIN	(1.27) .050		
11-25	-0045-0059	R.F.M.													
2-10	-0071-0079	R.F.M.				(3.30) .130	(6.10) .240		30 GOLD	(2.54) .100		TIN	(1.27) .050		
11-25	-0080-0094	R.F.M.													
2-10	-0141-0149	R.F.M.				(5.21) .205	(6.10) .240		15 GOLD	(2.54) .100		TIN	(1.27) .050		
11-25	-0150-0164	NOT TOOLED													
2-10	-0176-0184	R.F.M.				(5.21) .205	(6.10) .240		30 GOLD	(2.54) .100		TIN	(1.27) .050		
11-25	-0185-0199	NOT TOOLED													

CIRCUIT SIZE	ASSEMBLY ITEM NUMBER	ASSEMBLY ITEM NUMBER	ASSEMBLY ITEM NUMBER	ASSEMBLY ITEM NUMBER	ASSEMBLY ITEM NUMBER
2	70545-0001	70545-0036	70545-0071	70545-0141	70545-0176
3	70545-0002	70545-0037	70545-0072	70545-0142	70545-0177
4	70545-0003	70545-0038	70545-0073	70545-0143	70545-0178
5	70545-0004	70545-0039	70545-0074	70545-0144	70545-0179
6	70545-0005	70545-0040	70545-0075	70545-0145	70545-0180
7	70545-0006	70545-0041	70545-0076	70545-0146	70545-0181
8	70545-0007	70545-0042	70545-0077	70545-0147	70545-0182
9	70545-0008	70545-0043	70545-0078	70545-0148	70545-0183
10	70545-0009	70545-0044	70545-0079	70545-0149	70545-0184
11	70545-0010	70545-0045	70545-0080		
12	70545-0011	70545-0046	70545-0081		
13	70545-0012	70545-0047	70545-0082		
14	70545-0013	70545-0048	70545-0083		
15	70545-0014	70545-0049	70545-0084		
16	70545-0015	70545-0050	70545-0085		
17	70545-0016	70545-0051	70545-0086		
18	70545-0017	70545-0052	70545-0087		
19	70545-0018	70545-0053	70545-0088		
20	70545-0019	70545-0054	70545-0089		
21	70545-0020	70545-0055	70545-0090		
22	70545-0021	70545-0056	70545-0091		
23	70545-0022	70545-0057	70545-0092		
24	70545-0023	70545-0058	70545-0093		
25	70545-0024	70545-0059	70545-0094		

CHG D DIM -0141-0199
EC NO: UCP2007-0420
DRWN:DMORGAN 2006/09/15
CH'KD:MSIBARRA 2006/09/15
APPR:SMILLER 2006/09/19
DESCRIPTION
H
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.005
2 PLACES	± 0.13	±.01
1 PLACE	± 0.25	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: ---
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: WGM DATE: 07/12/96
CHECKED BY: WGM DATE: 07/12/96
APPROVED BY: DJB DATE: 07/12/96
MATERIAL NO.: SEE CHART
SIZE: C

TITLE: SALES ASSY, SL VERTICAL HEADER W/LATCH&TRI-PEGS (2.54)/.100 CENTERS

MOLEX INCORPORATED

DOCUMENT NO.: SDA-70545-****
SHEET NO.: 3 OF 4